“Benefits to Working with a University Research Lab in the Post Recession Era:
How Universities and Industry can Partner for Success”

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Abstract:
The post recession economy has altered the relationship between commercial companies and universities. Company sponsored funding at the university has decreased and the expected return of any investment has increased. There are many benefits, however, for companies who interact with university research labs and this talk will discuss those opportunities. The benefits include recruiting, joint proposals, technology and prototype development, technology transfer, continuing education, and consulting. One typical example is the Industrial Program at the Wireless Integrated MicroSensing and Systems Research Center (WIMS²) at the University of Michigan. At WIMS² there is a membership program for companies and a dedicated staff member who is responsible for facilitating interactions with the faculty and fulfilling requests from industry.

The talk will discuss how both small and large companies can profitably use an industrial membership program to recruit, transfer technology, write research proposals, and develop new technologies and products.

Speaker’s Biography:
Andrew “Andy” Oliver received the B.S.E.E. degree with distinction from Iowa State University, and the M.S. and Ph.D. in Electrical Engineering from the University of Michigan. His industrial experience includes nine years at Sandia National Laboratories in Albuquerque, New Mexico, where he worked on the design, fabrication, and packaging of surface micromachines. After this he contributed to ICx Ion Optics in Waltham, Massachusetts, where he designed MEMS infrared based gas detectors and developed a wafer-level vacuum package technology. He also has SBIR and startup company experience. He taught a three-credit, graduate-level course on the packaging of MEMS devices at the University of New Mexico as well as courses for the Boston Section of IEEE. In 2011, he joined the University of Michigan’s Center for Wireless Integrated MicroSensing and Systems as the Research Liaison. Andy is a recipient of an R&D 100 award for one of the 100 most technology significant new products of 2008, has one patent, and has authored multiple journal papers, book chapters, and conference papers as well as being a senior member of IEEE.

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